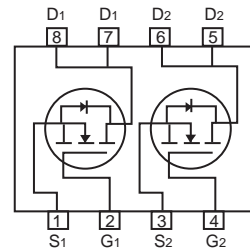
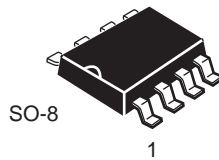


## Dual N-Channel Enhancement Mode Field Effect Transistor

### FEATURES

- 40V, 6.3A,  $R_{DS(ON)} = 30m\Omega$  @  $V_{GS} = 10V$ .  
 $R_{DS(ON)} = 45m\Omega$  @  $V_{GS} = 4.5V$ .
- Super high dense cell design for extremely low  $R_{DS(ON)}$ .
- High power and current handling capability.
- Lead free product is acquired.
- Surface mount Package.



### ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$ unless otherwise noted

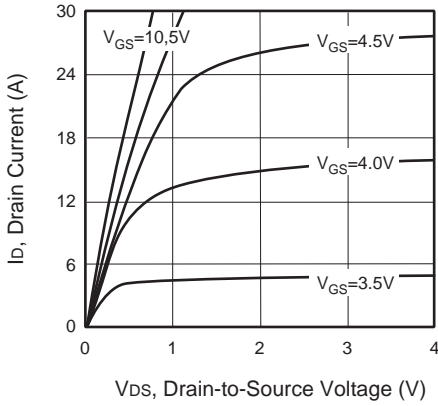
Parameter	Symbol	Limit	Units
Drain-Source Voltage	$V_{DS}$	40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	V
Drain Current-Continuous	$I_D$	6.3	A
Drain Current-Pulsed <sup>a</sup>	$I_{DM}$	20	A
Maximum Power Dissipation	$P_D$	2.0	W
Operating and Store Temperature Range	$T_J, T_{stg}$	-55 to 150	$^\circ\text{C}$

### Thermal Characteristics

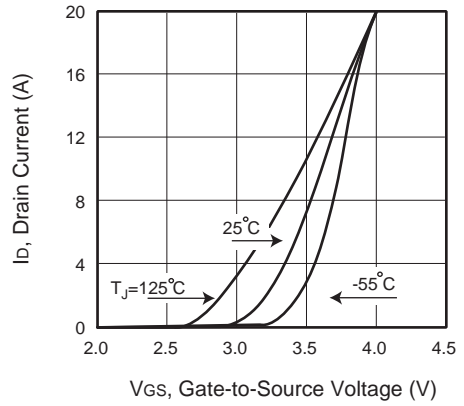
Parameter	Symbol	Limit	Units
Thermal Resistance, Junction-to-Ambient <sup>b</sup>	$R_{\theta JA}$	62.5	$^\circ\text{C/W}$

## Electrical Characteristics $T_A = 25^\circ\text{C}$ unless otherwise noted

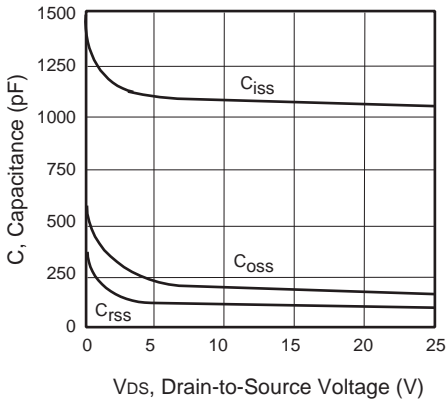
Parameter	Symbol	Test Condition	Min	Typ	Max	Units	
<b>Off Characteristics</b>							
Drain-Source Breakdown Voltage	$BV_{DSS}$	$V_{GS} = 0V, I_D = 250\mu A$	40			V	
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 40V, V_{GS} = 0V$			1	$\mu A$	
Gate Body Leakage Current, Forward	$I_{GSSF}$	$V_{GS} = 20V, V_{DS} = 0V$			100	nA	
Gate Body Leakage Current, Reverse	$I_{GSSR}$	$V_{GS} = -20V, V_{DS} = 0V$			-100	nA	
<b>On Characteristics<sup>c</sup></b>							
Gate Threshold Voltage	$V_{GS(th)}$	$V_{GS} = V_{DS}, I_D = 250\mu A$	1		3	V	
Static Drain-Source	$R_{DS(on)}$	$V_{GS} = 10V, I_D = 6A$		24	30	$m\Omega$	
On-Resistance		$V_{GS} = 4.5V, I_D = 5A$		35	45	$m\Omega$	
Forward Transconductance	$g_{FS}$	$V_{DS} = 5V, I_D = 6A$		9		S	
<b>Dynamic Characteristics<sup>d</sup></b>							
Input Capacitance	$C_{iss}$	$V_{DS} = 20V, V_{GS} = 0V, f = 1.0\text{ MHz}$		1050		pF	
Output Capacitance	$C_{oss}$				155		pF
Reverse Transfer Capacitance	$C_{rss}$				95		pF
<b>Switching Characteristics<sup>d</sup></b>							
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = 20V, I_D = 6A, V_{GS} = 10V, R_{GEN} = 3\Omega$		14	30	ns	
Turn-On Rise Time	$t_r$			10	20	ns	
Turn-Off Delay Time	$t_{d(off)}$			17	35	ns	
Turn-On Fall Time	$t_f$			18	35	ns	
Total Gate Charge	$Q_g$	$V_{DS} = 20V, I_D = 6A, V_{GS} = 10V$		20.5	27	nC	
Gate-Source Charge	$Q_{gs}$			3.5		nC	
Gate-Drain Charge	$Q_{gd}$			4.0		nC	
<b>Drain-Source Diode Characteristics and Maximum Ratings</b>							
Drain-Source Diode Forward Current <sup>b</sup>	$I_S$				1.0	A	
Drain-Source Diode Forward Voltage <sup>c</sup>	$V_{SD}$	$V_{GS} = 0V, I_S = 1.0A$			1.2	V	
<b>Notes :</b> a.Repetitive Rating : Pulse width limited by maximum junction temperature. b.Surface Mounted on FR4 Board, $t \leq 10\text{ sec}$ . c.Pulse Test : Pulse Width $\leq 300\mu s$ , Duty Cycle $\leq 2\%$ . d.Guaranteed by design, not subject to production testing.							



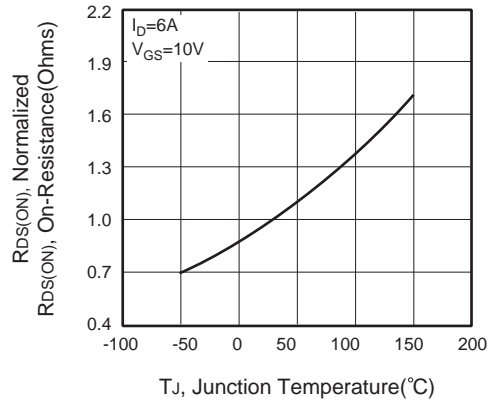
**Figure 1. Output Characteristics**



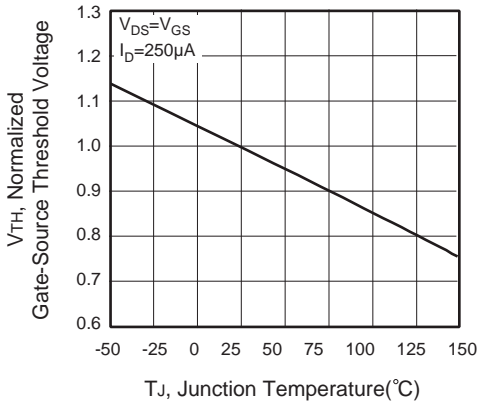
**Figure 2. Transfer Characteristics**



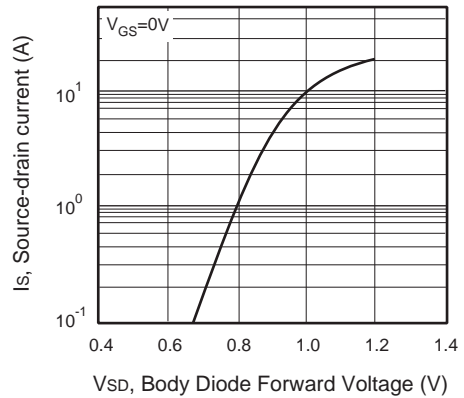
**Figure 3. Capacitance**



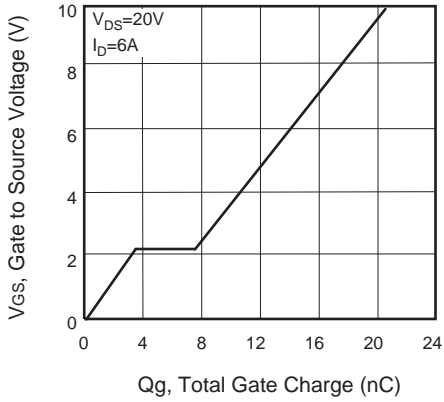
**Figure 4. On-Resistance Variation with Temperature**



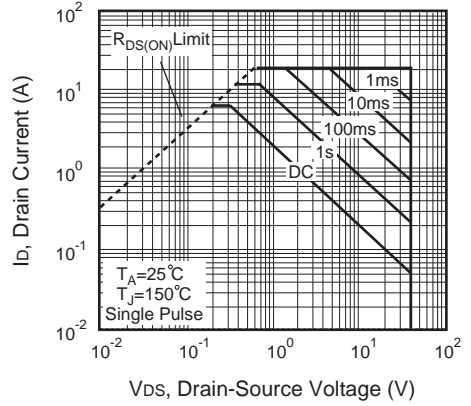
**Figure 5. Gate Threshold Variation with Temperature**



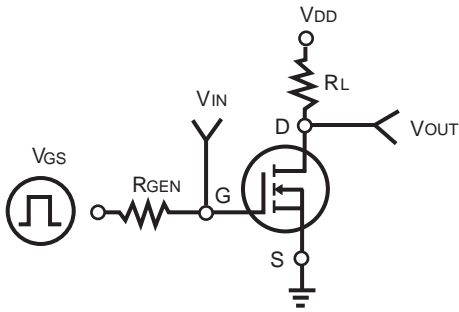
**Figure 6. Body Diode Forward Voltage Variation with Source Current**



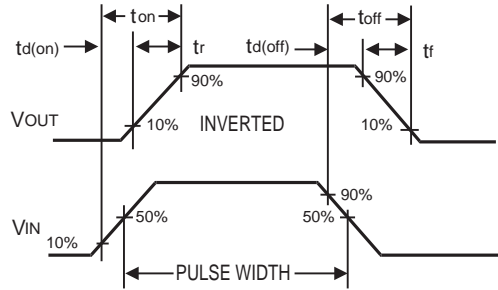
**Figure 7. Gate Charge**



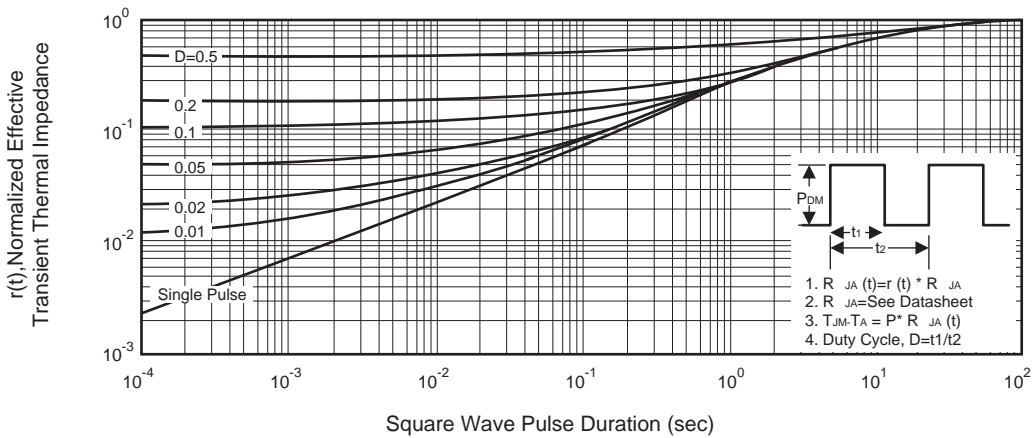
**Figure 8. Maximum Safe Operating Area**



**Figure 9. Switching Test Circuit**



**Figure 10. Switching Waveforms**



**Figure 11. Normalized Thermal Transient Impedance Curve**